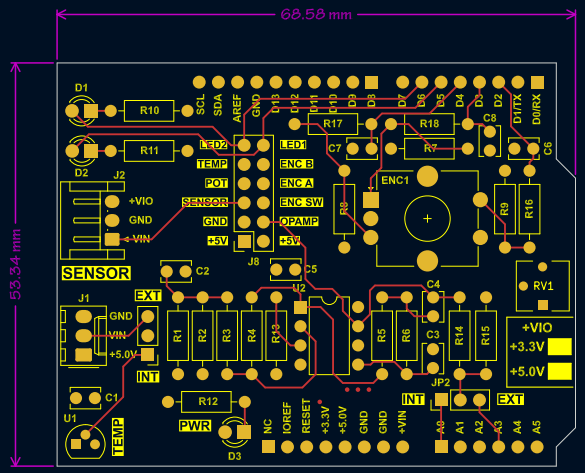


LAYER 1

BOARD CHARACTERISTICS			
Copper layer count:	4	Board thickness:	1.6000 mm
Board overall dimensions:	68.5800 mm x 53.3400 mm		
Min track/spacing:	0.2500 mm / 0.4500 mm	Min hole diameter:	0.3000 mm
Copper finish:	None	Impedance control:	No
Castellated pads:	No	Press-fit pads:	No
Plated board edge:	No	Edge card connectors:	No

Layer Name	Type	Material	Thickness	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top silk screen	Not specified	Not specified	White	1	0
F.Paste	Top solder paste		Not specified		1	0
F.Mask	Top solder mask	Not specified	0.01 mm	Blue	3.3	0
F.Cu	Copper		0.035 mm		1	0
Dielectric 1	Prepreg	FR4	0.1 mm	FR4 natural	4.5	0.02
In1.Cu	Copper		0.035 mm		1	0
Dielectric 2	Core	FR4	1.24 mm	FR4 natural	4.5	0.02
In2.Cu	Copper		0.035 mm		1	0
Dielectric 3	Prepreg	FR4	0.1 mm	Not specified	4.5	0.02
B.Cu	Copper		0.035 mm		1	0
B.Mask	Bottom solder mask	Not specified	0.01 mm	Blue	3.3	0
B.Paste	Bottom solder paste		Not specified		1	0
B.Silkscreen	Bottom silk screen	Not specified	Not specified	White	1	0

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Sheet:

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Title: Analog Shield

Size: A	Date: 2023-05-04	Rev: C
KiCad E.D.A. 10.0.3		Id: 1/1